LTR	ZONE	REVISION	DATE	EQUIP TYPE	APPROVAL

26> CONNECT PIN 6 TO PIN 7 USING 30 DEG (ITEM 13) AND WIRE (ITEM 14). REMOVE INSULATION FROM WIRE AND USE ONLY TWO (2) CONDUCTOR STRANDS. TRIM OFF EXCESS WIRE.

25> ATTACH HEAT SINK (ITEM 7) TO THIS COMPONENT USING ADHESIVE (ITEM 6).

24> APPLY 3140 CONFORMAL COATING (ITEM 5) THINNED WITH NAPTHA (ITEM 8) TO BOTH SIDES OF BOARD PER NHB 5300.4 (3J) PARA 3J500, 3J501, AND 3J502.

23> PRIME PER NHB 5300.4 (3J) PARA 3J402 USING 1204 PRIMER (ITEM 2).

22> PERMANENT INK MARK P/N AND SER NO IN .125 HIGH CHARACTERS WITH MARKING INK (ITEM 3) PER JSC-SPEC-M-1, PARA 3.7.8. THE FIRST PRODUCTION RUN WILL BEGIN WITH S/N 1001 PER JSC 8500.3. LOCATED APPROXIMATELY AS SHOWN.

21> PERMANENTLY INK STAMP ESD SYMBOL IN APPROX. LOCATION SHOWN, USING WHITE MARKING INK (ITEM 3).

20> MASK OFF AREA AS SHOWN AND DO NOT APPLY CONFORMAL COAT TO THIS AREA.

19> COVER CONNECTOR FACE WITH TAPE (ITEM 4) BEFORE CONFORMAL COATING. SECURE TAPE TO PWB WITH A DAB OF ADHESIVE (ITEM 15). DO NOT REMOVE TAPE AFTERWARDS, LEAVE COMPONENT COVERED.

18> SECURE INTEGRATED CIRCUIT TO SOCKET AND SECURE JUMPER TO PIN HEADER USING ADHESIVE (ITEM 15) - SEE DETAIL H. THEN COVER COMPONENT COMPLETELY WITH TAPE (ITEM 4). SECURE TAPE TO PWB WITH A DAB OF ADHESIVE (ITEM 15) BEFORE CONFORMAL COATING. DO NOT REMOVE TAPE AFTERWARDS, LEAVE COMPONENT COVERED.

17> REMOVE SCREWS. REINSTALL, USING ADHESIVE (ITEM 12) PER JSCM 5500 M/P-10 ON THREADS.

16> APPLY STAKING ADHESIVE (ITEM 15) TO COMPONENTS C33-C38, C57, C58, U11, U26 , U35 AND L1 PER NHB 5300.4 (3J), PARA 3J600, 3J601 AND 3J602.

15> SET JUMPERS TO 'TRST' AND 'TCK'.

14> SET JUMPER TO "I12".

13> SET JUMPERS TO "A12", "A11", "A10", "A8", "A7", "A6", AND "A5".

12> SET JUMPER TO "P".

11> SET JUMPER TO "MS0".

10> VERIFY THAT THE PART NUMBER OF THE CHIP INSTALLED AT U35 IS R3.0.

9> LOCTITE CORP., NEWINGTON, CT.

8> ACCURATE SCREW MACHINE CO., FAIRFIELD, NJ.

7> PARKS CORP., SOMERSET, MA.

6> WAKEFIELD ENGINEERING, WAKEFIELD, MA.

5> NOT USED.

4> 3M CO., ST. PAUL, MN.

3> INDEPENDENT INK INC., GARDENA CA.

2> DOW CORNING, MIDLAND, MI.

1> BITTWARE RESEARCH SYSTEMS, CONCORD, NH.

FLAG NOTES:

6. ALL REFERENCED SPECIFICATIONS AND STANDARDS SHALL BE OF THE LATEST REVISION LEVEL OR AS SPECIFIED IN THE PROCUREMENT DOCUMENT. IN THE CASE OF CONFLICT, THE PROCUREMENT DOCUMENT SHALL TAKE PRECEDENCE.
5. SOLDER PER NAS 5300.4 (3A-2).
4. THIS ASSEMBLY CONTAINS SOME COMPONENTS THAT ARE ESD SENSITIVE. HANDLE PER NHB 5300.4 (3L).
3. THIS ASSEMBLY CONTAINS NO FRACTURE CRITICAL ELEMENTS.
2. CLEANLINESS REQUIREMENTS PER SN-C-0005, GC LEVEL.
1. INTERPRET PER JPG 8500.4.

NOTES: UNLESS OTHERWISE SPECIFIED

ALTERED ITEM DRAWING

QTY	PART NUMBER	DESCRIPTION	MATERIAL	SPECIFICATION	ITEM
AR	3145	ADHESIVE	RTV	2	15
1IN	M22759/22-26-0	WIRE, STRANDED	[illegible]	MIL-W-22759	14
AR	63/37.025P3REL15	SOLDER		QQ-S-571	13
AR	222	ADHESIVE	POLYGLYCOL DIMETHACRYLATE POLYGLYCOL OLEATES	9	12
1	MS21043-06	NUT, SELF-LOCKING	CRES 138-32UNJC-3B		11
2	NAS620C6	WASHER, FLAT REDUCED O.D.	CRES FOR NO6		10
1	17704-H-SS-12	GUIDE PIN	STAINLESS STEEL	8	9
AR	2713	THINNER, NAPTHA		7	8
2	658-25AB	HEAT SINK	6061-T6 ALUMINUM	6	7
AR	EP21TCHT-1(A+B)	ADHESIVE	EPOXY NOVOLAC RESIN, POLYAMIDE RESIN	4	6
AR	3140	CONFORMAL COATING		2	5
AR	5413	TAPE	POLYIMIDE/SILICONE	4	4
AR	73X WHITE	INK, MARKING		3	3
AR	1204	PRIMER		2	2
1	SNAG-4062-112	SNAGGLETOOTH PWB		1	1
-	-301	DIGITAL SIGNAL PROCESSOR BOARD ASSY			

SIGNATURES	DATE
DR C. NUNEZ	5/29/97
ENG	7/14/97
CHK	7/14/97
APP	7/14/97
DE	
MATE	
STRESS	7/16/97
AUTH	

NEXT ASSY: SDG46114973

CALC WT:

MOD FILE:

DRW FILE: F1:3971A.dwg

EQUIP TYPE
☒ FLT HDWR
☐ OTHER (SPECIFY)
☐ APPLICABLE ESE

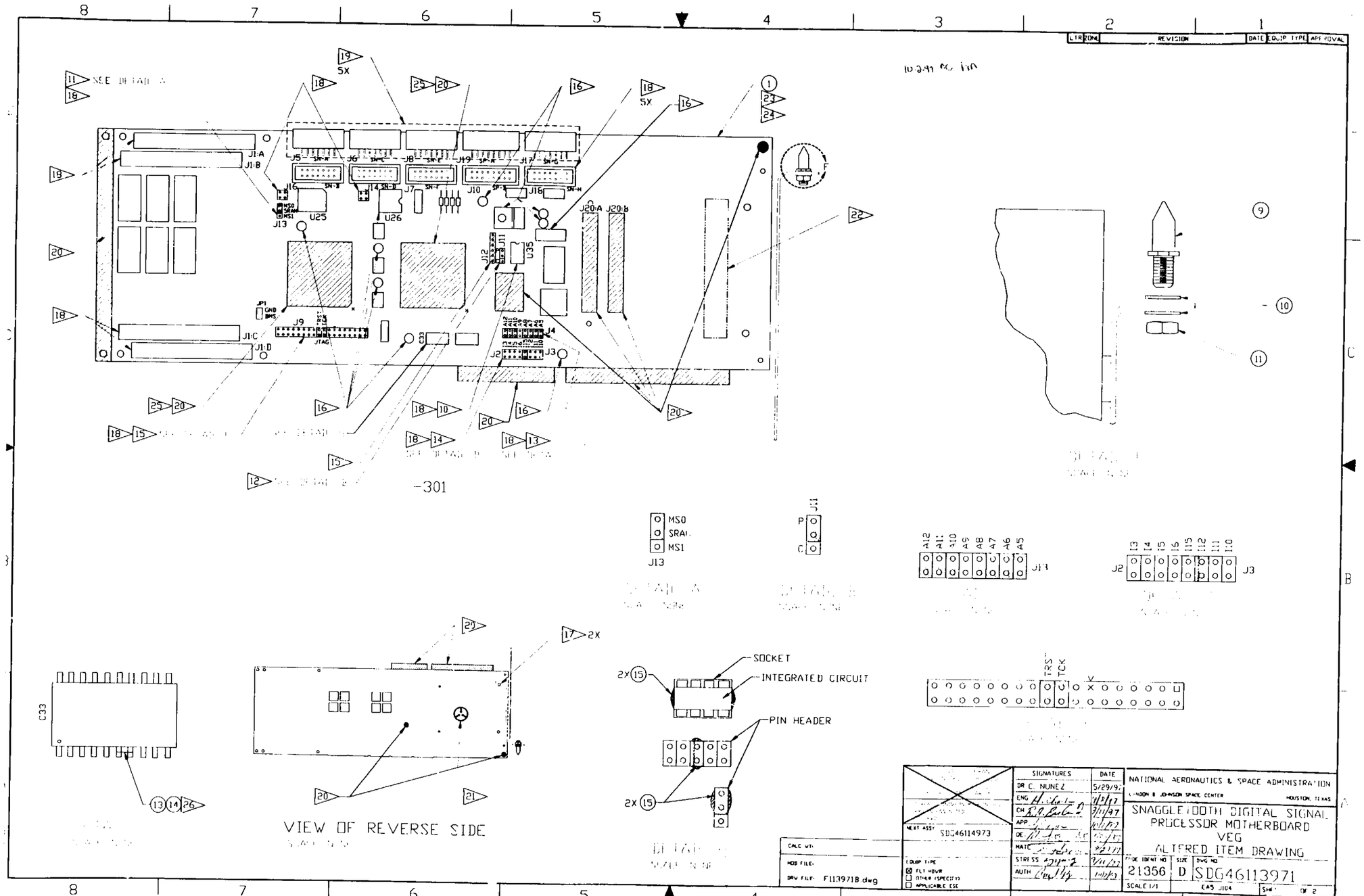
NATIONAL AERONAUTICS & SPACE ADMINISTRATION
LYNDON B. JOHNSON SPACE CENTER HOUSTON, TEXAS

SNAGGLETOOTH DIGITAL SIGNAL PROCESSOR MOTHERBOARD VEG
ALTERED ITEM DRAWING

DOC IDENT NO: 21356 | SIZE: D | DWG NO: SDG46113971

SCALE: 1/1 | EAS J104 | SHEET 1 OF 2

515



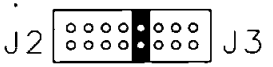
SEE DETAIL A
-301
MS0
SRAM
MS1
J13
J11
P
C
A12 A11 A10 A9 A8 A7 A6 A5
J13
J2
I3 I4 I5 I6 I15 I12 I11 I10
J3
TRST
TCK
SOCKET
INTEGRATED CIRCUIT
PIN HEADER
2X 15
C33
VIEW OF REVERSE SIDE
NEXT ASSY SDG46114973
CALC WT:
MOD FILE:
DRW FILE: F113971B.dwg
EQUIP TYPE
FLT HDWR
OTHER (SPECIFY)
APPLICABLE ESE
SIGNATURES
DATE
DR C. NUNEZ 5/29/97
ENG
CH 3/11/97
APP
DE
MATL
STRESS
AUTH
NATIONAL AERONAUTICS & SPACE ADMINISTRATION
LYNDON B. JOHNSON SPACE CENTER
HOUSTON, TEXAS
SNAGGLETOOTH DIGITAL SIGNAL
PROCESSOR MOTHERBOARD
VEG
ALTERED ITEM DRAWING
CODE IDENT NO 21356
SIZE D
DWG NO SDG46113971
SCALE 1/1
EAS J104
SHEET OF 2

516

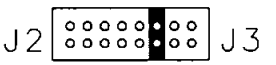
DCN NUMBER			DRAWING CHANGE NOTICE					SHEET 1 OF 1
DRAWING NO. SDG46113971	REV NC	SEQ.# 01	REASON FOR CHANGE	ORIGINATOR	DATE	QE	DATE
DRAWING TITLE SNAGGLETOOTH DIGITAL SIGNAL PROCESSOR MOTHERBOARD, VEG -ALTERED ITEM DRAWING			DRAFTING ERROR	E MILLER	4/28/98	M. IWASA	5/5/98
				ENG B RUIZ	4/23/98	MATL H. KAO	4/30/98
				CH R BULAND	4/17/98	STRESS F. YUNG	4/30/98
PROJECT J104-HRF/VEG				APP F. BOOKER	5/6/98		
				AUTH		FINAL APP	

1. ON SHEET 1, FLAG NOTE 18,
   WAS: "...CIRCUIT TO SOCKET AND SECURE..."
   IS: "...CIRCUIT TO SOCKET OR SECURE..."
2. ON SHEET 2, ZONE B-6, CHANGE FLAG NOTE 15 TO 18.
3. IN ZONE C-5, MOVE JUMPER TO "I12" AS SHOWN.

WAS:



IS:



	PART NUMBER	DESCRIPTION	MATERIAL	SPECIFICATION		(IS) (WAS)

DWG FILE: 46113971NC01 PROJECT: B100/B104 HRF LIBRARY: NON ASC DRAWINGS